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(12) United States Design Patent

Kang et al.

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(54) **SEAL MEMBER FOR USE IN SEMICONDUCTOR PRODUCTION APPARATUS**

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(73) Assignee: **Valqua, Ltd.**, Tokyo (JP)

(**) Term: **15 Years**

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Related U.S. Application Data

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(30) **Foreign Application Priority Data**

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(51) **LOC (13) Cl.** **23-01**

(52) **U.S. Cl.**

USPC **D23/269**

CPC ***F16J 15/025*** (2013.01)

(58) **Field of Classification Search**

USPC D15/7, 9, 11, 17, 21, 28, 123, 199; D23/269, 386, 259; D8/349; 277/602–626; 285/95, 109, 336, 910, 918

CPC F16K 51/02; F16J 15/025; F16J 15/0887; F16J 15/104; F16J 15/128

See application file for complete search history.

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(57) **CLAIM**

The ornamental design for a seal member for use in semiconductor production apparatus, as shown and described.

DESCRIPTION

FIG. **1** is a perspective view of a seal member for use in semiconductor production apparatus, showing our new design;

FIG. **2** is a front elevation view thereof;

FIG. **3** is a rear elevation view thereof;

FIG. **4** is a left side elevation view thereof;

FIG. **5** is a right side elevation view thereof;

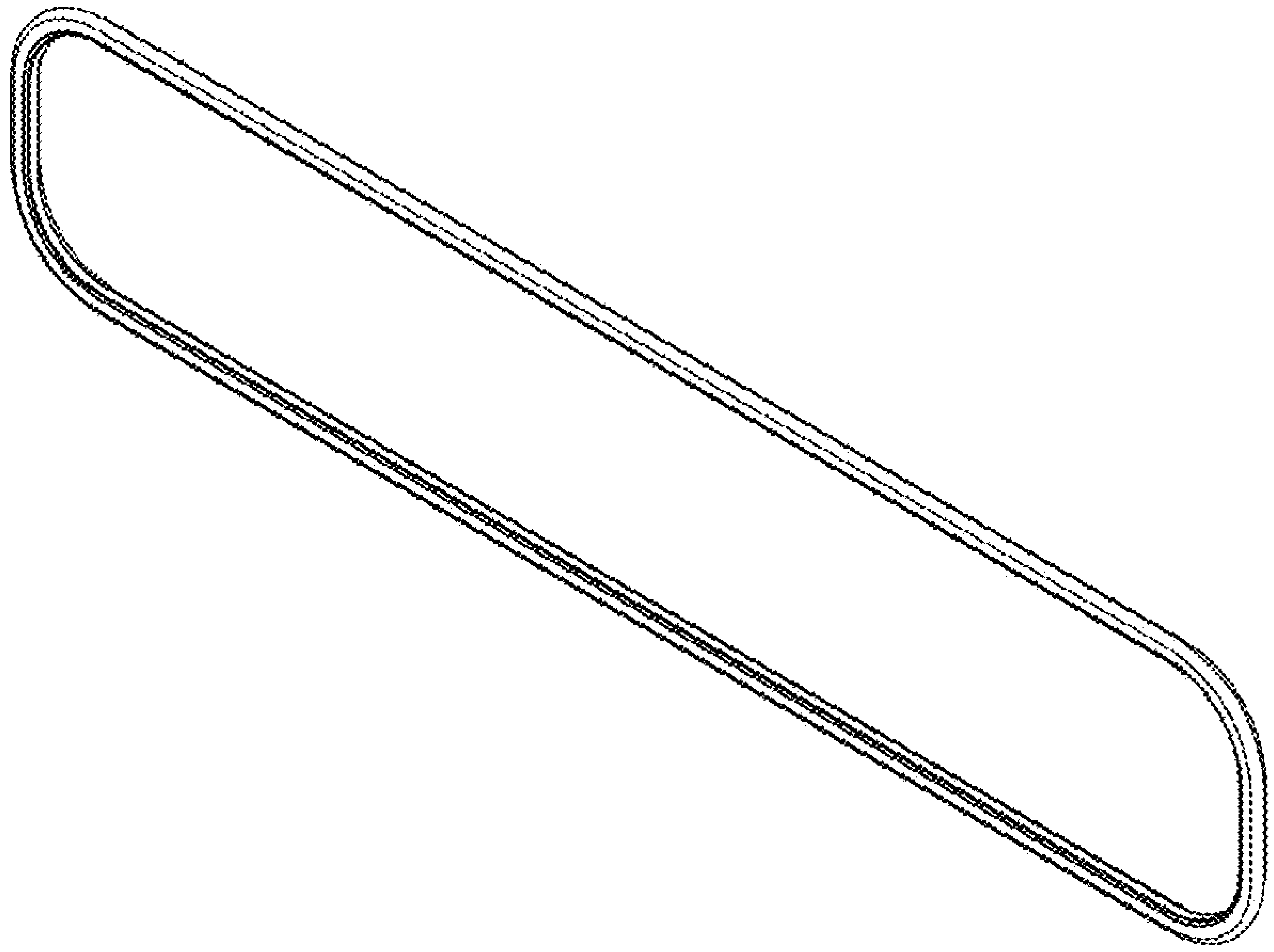
FIG. **6** is a top view thereof;

FIG. **7** is a bottom view thereof;

FIG. **8** is a cross-sectional view thereof; and,

FIG. **9** is an enlarged cross-sectional view of a portion thereof.

1 Claim, 9 Drawing Sheets



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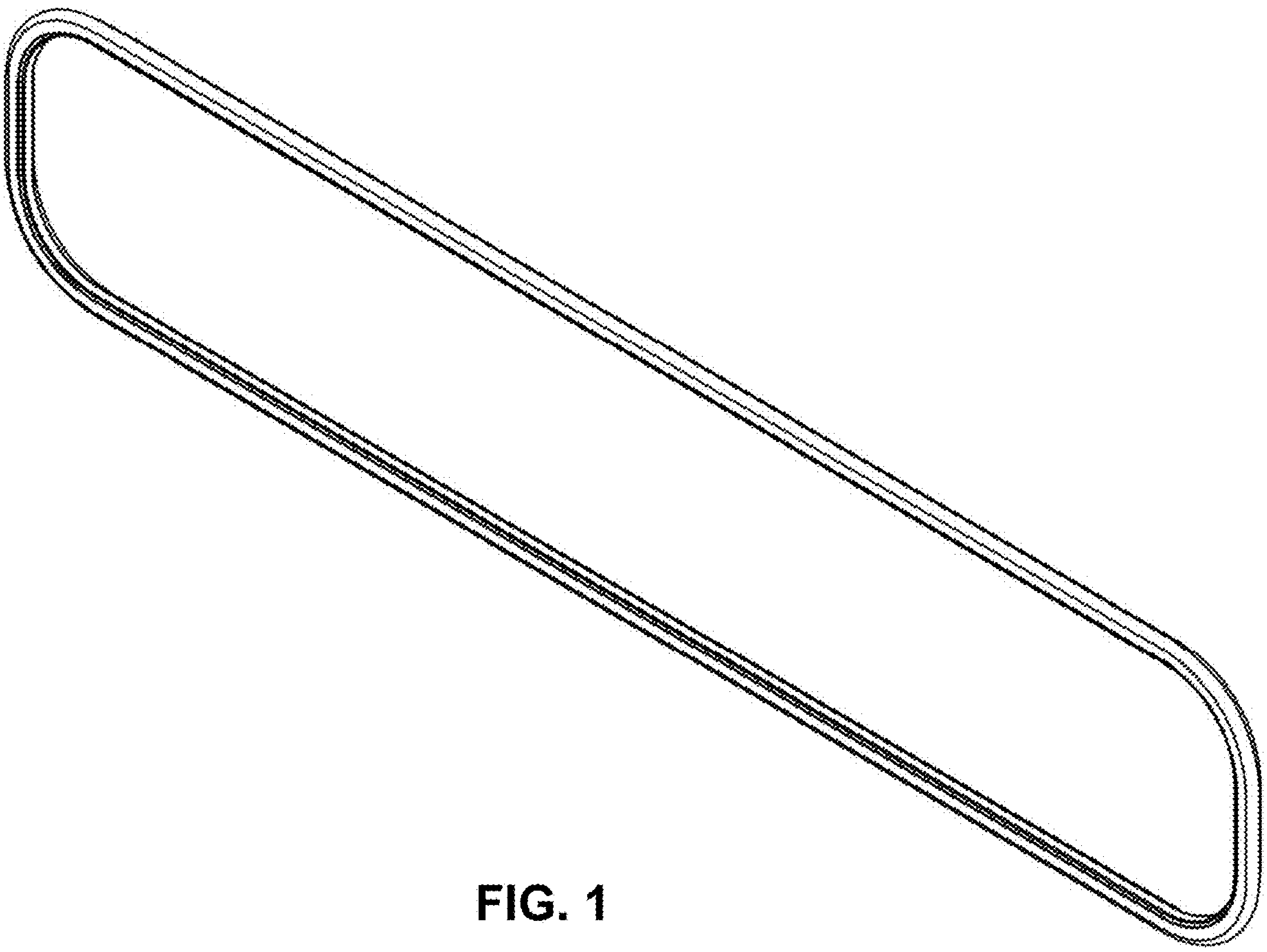

FIG. 1

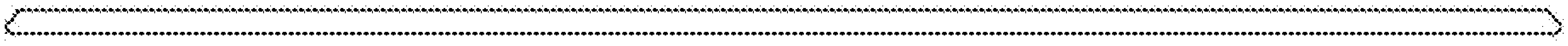

FIG. 2

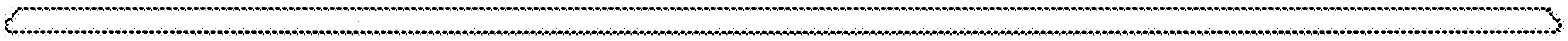

FIG. 3

FIG. 4

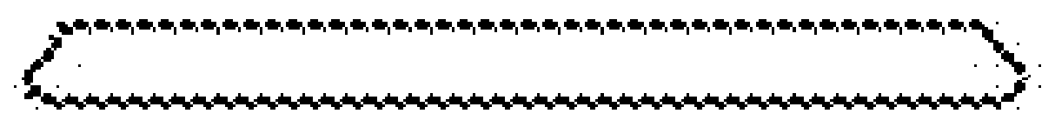

FIG. 5

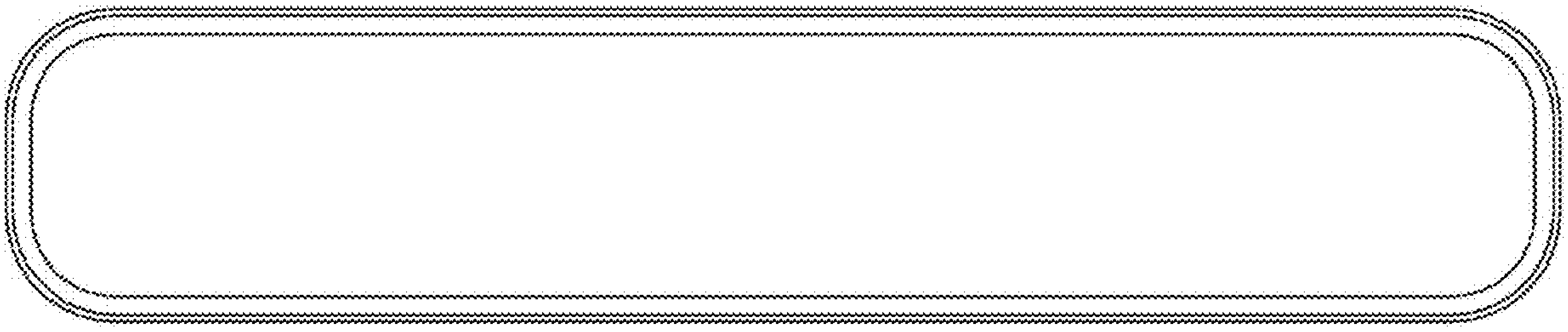

FIG. 6

FIG. 7

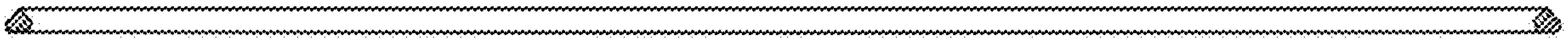

FIG. 8

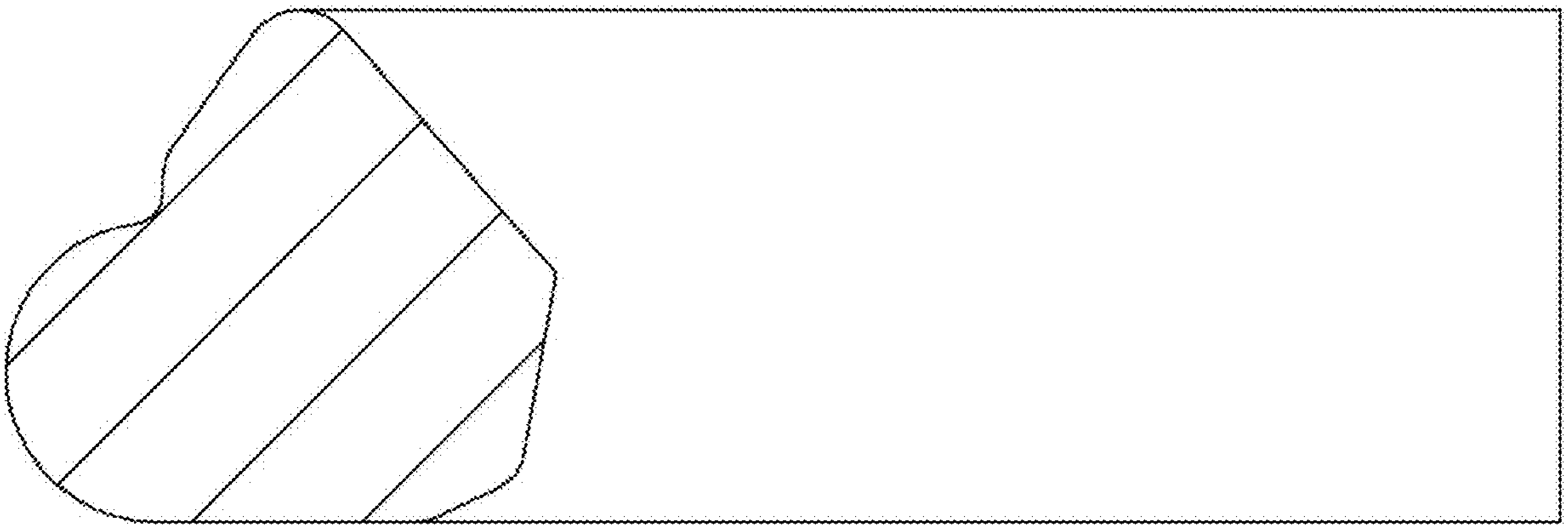

FIG. 9